

# METHOD FOR MANUFACTURING LIGHT EMITTING DIODE UTILIZING TRANSPARENT SUBSTRATE AND METAL BONDING TECHNOLOGY AND STRUCTURE THEREOF

## ABSTRACT OF THE DISCLOSURE

A method for manufacturing the light emitting diode utilizing the transparent substrate and the metal bonding technology is provided. The method includes steps of providing a growing substrate, forming a semiconductor structure on the growing substrate, forming a metal bonding layer on the semiconductor structure, bonding a transparent substrate to the semiconductor structure via the metal bonding layer, removing the growing substrate, and forming a first electrode and a second electrode on the semiconductor structure and the transparent substrate respectively.